WESTCODE

Date:- 2 Jan, 2002

Data Sheet Issue:- 1

Phase Control Thyristor Types N1351VC400 to N1351VC450

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V _{DRM}	Repetitive peak off-state voltage, (note 1)	4000-4500	V
V _{DSM}	Non-repetitive peak off-state voltage, (note 1)	4000-4500	V
V _{RRM}	Repetitive peak reverse voltage, (note 1)	4000-4500	V
V _{RSM}	Non-repetitive peak reverse voltage, (note 1)	4100-4600	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I _{T(AV)}	Mean on-state current. T _{sink} =55°C, (note 2)	1351	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 2)	944	А
I _{T(AV)}	Mean on-state current. T _{sink} =85°C, (note 3)	587	А
I _{T(RMS)}	Nominal RMS on-state current. T _{sink} =25°C, (note 2)	2641	А
I _{T(d.c.)}	D.C. on-state current. T _{sink} =25°C, (note 4)	2352	А
I _{TSM}	Peak non-repetitive surge $t_p=10ms$, $V_{rm}=0.6V_{RRM}$, (note 5)	17500	А
I _{TSM2}	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V, (note 5)	20000	А
l ² t	$I^{2}t$ capacity for fusing t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)	1.53×10 ⁶	A ² s
l ² t	$I^{2}t$ capacity for fusing t _p =10ms, V _{rm} ≤10V, (note 5)	2.00×10 ⁶	A ² s
al: /al#	Maximum rate of rise of on-state current (repetitive), (Note 6)	150	A/µs
di⊤/dt	Maximum rate of rise of on-state current (non-repetitive), (Note 6)	300	A/µs
V _{RGM}	Peak reverse gate voltage	5	V
P _{G(AV)}	Mean forward gate power	4	W
P _{GM}	Peak forward gate power	30	W
V_{GD}	Non-trigger gate voltage, (Note 7)	0.25	V
Тнs	Operating temperature range	-40 to +125	°C
T _{stg}	Storage temperature range	-40 to +150	°C

Notes: -

- 1) De-rating factor of 0.13% per °C is applicable for T_j below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180° half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, $125^{\circ}C T_{j}$ initial.
- 6) $V_D=67\% V_{DRM}$, $I_{TM}=1000A$, $I_{FG}=2A$, $t_r \le 0.5 \mu s$, $T_{case}=125^{\circ}C$.
- 7) Rated V_{DRM}.

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
Vtm	Maximum peak on-state voltage	-	-	3.0	I _{TM} =3220A	V
V ₀	Threshold voltage	-	-	1.20		V
r _S	Slope resistance	-	-	0.553		mΩ
dv/dt	Critical rate of rise of off-state voltage	1000	-	-	V_D =80% V_{DRM} , linear ramp, Gate O/C	V/µs
I _{DRM}	Peak off-state current	-	-	150	Rated V _{DRM}	mA
I _{RRM}	Peak reverse current	-	-	150	Rated V _{RRM}	mA
V _{GT}	Gate trigger voltage	-	-	3.0	T 25°C V 10V L 24	V
I _{GT}	Gate trigger current	-	-	300	$T_j=25^{\circ}C, V_D=10V, I_T=3A$	mA
Iн	Holding current	-	-	1000	T _j =25°C	mA
t _{gd}	Gate controlled turn-on delay time	-	0.7	1.0	V _D =67%V _{DRM} , I _{TM} =1000A, di/dt=10A/µs,	μs
t _{gt}	Turn-on time	-	1.5	2.0	I _{FG} =2A, t _r =0.5μs, T _j =25°C	
Q _{rr}	Recovered Charge	-	1500	-		μC
Q _{ra}	Recovered Charge, 50% chord	-	900	1200	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs,	μC
Irm	Reverse recovery current	-	90	-	V _r =50V	А
t _{rr}	Reverse recovery time, 50% chord	-	14.0	-		μs
+	Turn-off time	-	350	-	I _{TM} =1000A, t _p =1000μs, di/dt=10A/μs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=20V/μs	
t _q		-	600	-	I _{TM} =1000A, t _p =1000µs, di/dt=10A/µs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=200V/µs	μs
D	Thermal registeres, junction to besteink	-	-	0.017	Double side cooled	K/W
Rth(j-hs)	Thermal resistance, junction to heatsink	-	-	0.034	Single side cooled	K/W
F	Mounting force	27	-	34		kN
Wt	Weight	-	1.0	-		kg

Notes: -

1) Unless otherwise indicated $T_j=125^{\circ}C$.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	V _{DRM} V _{DSM} V _{RRM} V	V _{RSM} V	V _D V _R DC V
40	4000	4100	2000
42	4200	4300	2040
44	4400	4500	2080
45	4500	4600	2100

2.0 Extension of Voltage Grades

This report is applicable to other and higher voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T_i below 25°C.

<u>4.0 Repetitive dv/dt</u> Standard dv/dt is 1000V/µs.

5.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 300A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

6.0 Gate Drive

The recommended pulse gate drive is 30V, 15Ω with a short-circuit current rise time of not more than 0.5µs. This gate drive must be applied when using the full di/dt capability of the device.

The pulse duration may need to be configured according to the application but should be no shorter than 20µs, otherwise an increase in pulse current may be needed to supply the necessary charge to trigger.

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7.0 Computer Modelling Parameters

7.1 Device Dissipation Calculations

Where $V_0=1.20V$, $r_s=0.553m\Omega$,

 R_{th} = Supplementary thermal impedance, see table below.

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle 30° 60° 90° 120° 180° 270° d.c.							d.c.
Square wave Double Side Cooled	0.027	0.0237	0.0218	0.0206	0.0192	0.0179	0.017
Square wave Single Side Cooled	0.0464	0.0428	0.0408	0.0395	0.038	0.0368	0.034
Sine wave Double Side Cooled	0.0233	0.0203	0.0191	0.0183	0.017		
Sine wave Single Side Cooled	0.042	0.039	0.0377	0.037	0.0355		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.46	2.45	2	1.73	1.41	1.15	1
Sine wave	3.98	2.78	2.22	1.88	1.57		

7.2 Calculating V_T using ABCD Coefficients

- The on-state characteristic I_T vs. V_T, on page 5 is represented in two ways;
- (i) the well established V_0 and r_s tangent used for rating purposes and
- (ii) a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

	125°C Coefficients						
Α	2.195803659						
B -0.395248246							
C 8.092×10 ⁻⁵							
D 6.58800679×10 ⁻²							

7.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}} \right)$$

Where p = 1 to *n*, *n* is the number of terms in the series and:

- t =Duration of heating pulse in seconds.
- r, Thermal resistance at time t.
- r_p = Amplitude of p_{th} term.
- τ_p = Time Constant of r_{th} term.

D.C. Double Side Cooled								
Term 1 2 3 4 5								
rp	8.74×10 ⁻³	4.03×10 ⁻³	2.09×10 ⁻³	1.38×10 ⁻³	0.981×10 ⁻³			
$ au_{ ho}$	1.328	0.182	0.0601	8.05×10 ⁻³	1.31×10 ⁻³			

D.C. Single Side Cooled								
Term	Term 1 2 3 4 5							
rp	0.0204	5.29×10 ⁻³	7.04×10 ⁻³	2.2×10 ⁻³	1.11×10 ⁻³			
$ au_{ ho}$	9.876	4.968	0.258	0.0137	1.33×10 ⁻³			

8.0 Reverse recovery ratings

i.e.

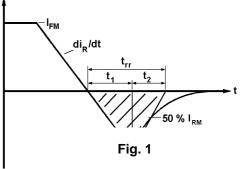
(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1.

(ii) Q_{rr} is based on a 150µs integration time.

$$Q_{rr} = \int_{0}^{150\mu s} i_{rr}.dt$$

K Factor = $\frac{t1}{t2}$



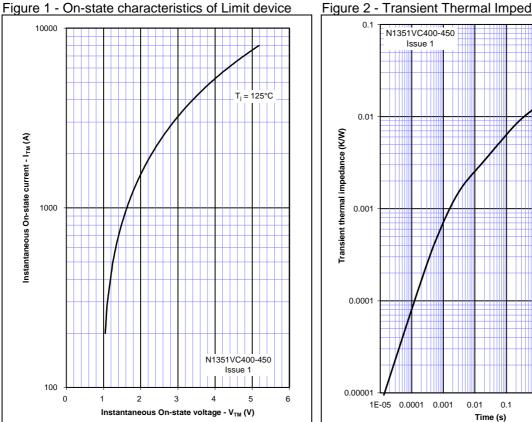


SSC 0.034K/W

DSC

0.017K/W

Curves



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Figure 3 - Gate Characteristics - Trigger Limits

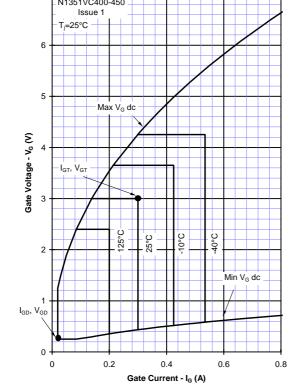


Figure 4 - Gate Characteristics - Power Curves

1

10

100

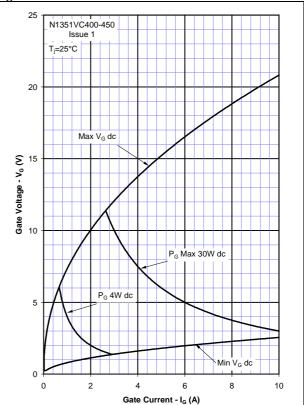
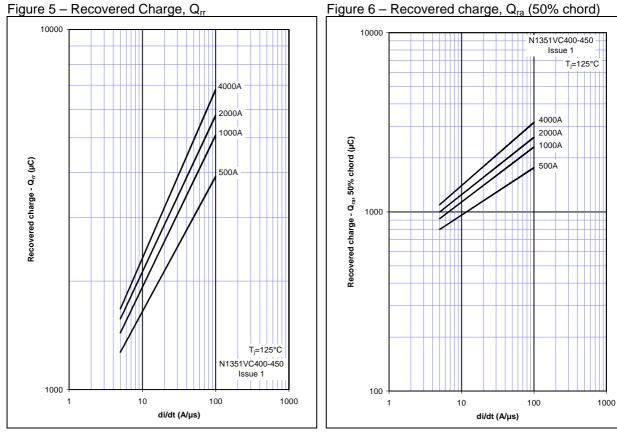


Figure 2 - Transient Thermal Impedance



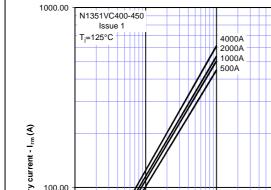
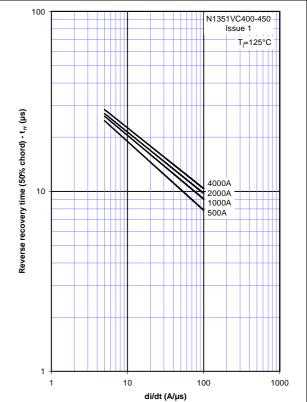
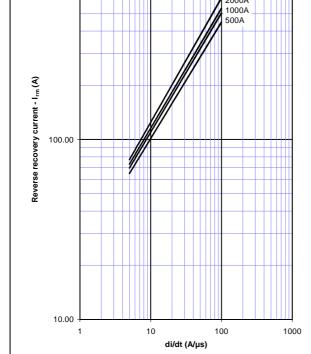


Figure 7 – Reverse recovery current, Irm

Figure 8 – Reverse recovery time, t_{rr} (50% chord)





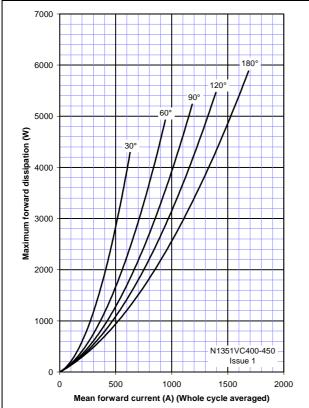


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)

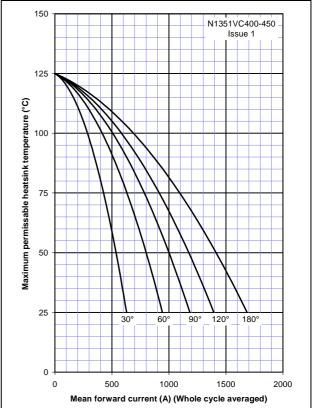


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

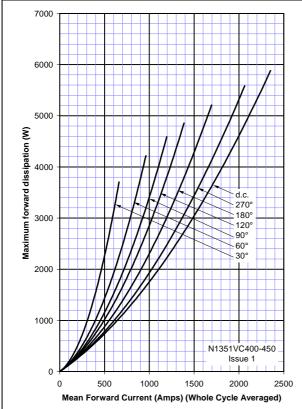
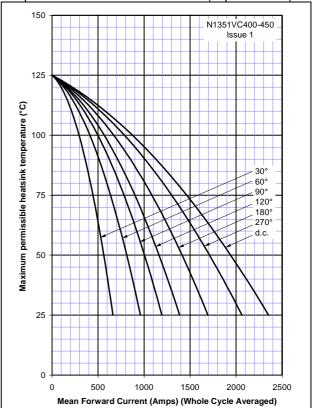


Figure 12 – On-state current vs. Heatsink temperature - Double Side Cooled (Square wave)



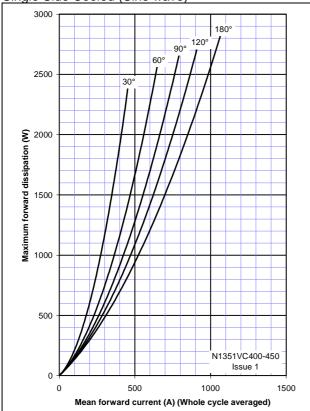


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

Figure 14 – On-state current vs. Heatsink temperature - Single Side Cooled (Sine wave)

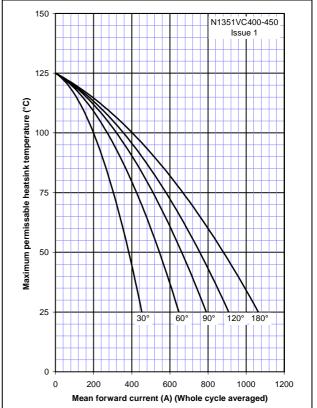


Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

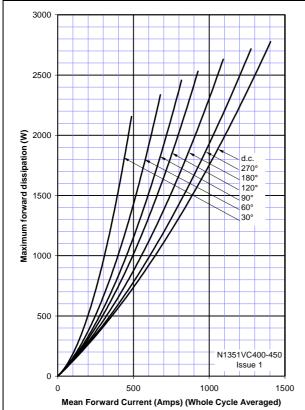


Figure 16 – On-state current vs. Heatsink temperature - Single Side Cooled (Square wave)

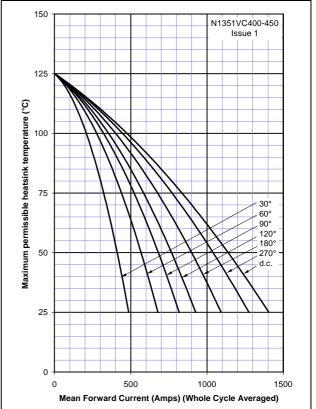
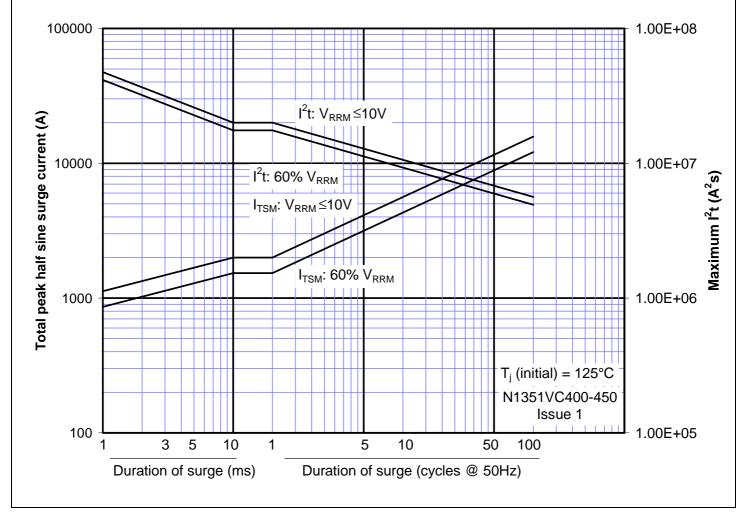


Figure 17 – Maximum surge and I²t Ratings



Outline Drawing & Ordering Information

